07 / 2022

LED630-03

- Light Emitting Dlode
- 630 nm, 12 mW
- Chip: AllnGaP, 350 x 350 μm, 1 pc.
- 5 mm Clear Molding, Epoxy Resin
- Viewing Angle: 28°





Description

LED630-03 contains one AllnGaP LED chip die with a typical peak wavelength of **630 nm** and radiation power of **12 mW**. It comes in Ø5 mm clear molding package with soldered lead frame (lead free) and lens molded with epoxy resin.

Maximum Ratings

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Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	P_D		120	mW	
Forward Current	IF		50	mA	
Pulse Forward Current *1	I _{FP}		100	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	R_{THJA}		300	K/W	
Junction Temperature	T_J		120	°C	
Operating Temperature	T_{CASE}	- 40	+ 100	°C	
Storage Temperature	T_{STG}	- 40	+ 100	°C	
Lead Solder Temperature *2	T_{SLD}		+ 265	°C	

^{*1} duty=1%, pulse width = 10 µs

Electro-Optical Characteristics (TCASE=25°C)

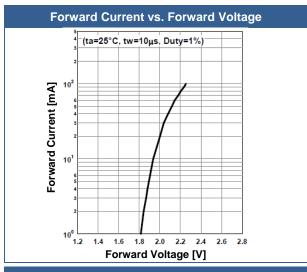
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =20mA	620		640	nm
Dominant Wavelength	λ_D	I _F =20mA		622		nm
Half Width	$\Delta \lambda$	I _F =20mA		15		nm
Forward Voltage	VF	I _F =20mA		2.0	2.3	V
	V_{FP}	I _{FP} =100mA		2.3		
Radiated Power *1	Po	I _F =20mA		12		mW
		I _{FP} =100mA		55		
Radiant Intensity *2	lE	I _F =20mA		46		mW/sr
		I _{FP} =100mA		210		
Luminous Flux	$oldsymbol{\phi}_V$	I _F =20mA		2400		mlm
Viewing Angle	2θ _{1/2}	I _F =20mA		28		deg.
Rise Time	t r	I _F =20mA		10		ns
Fall Time	t f	I _F =20mA		10		ns

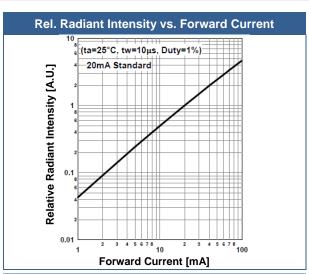
^{*1} measured by S3584-08

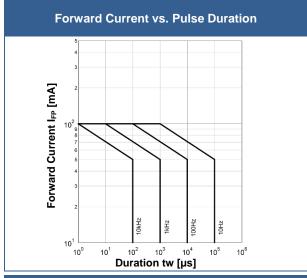
^{*2} must be completed within 5 seconds

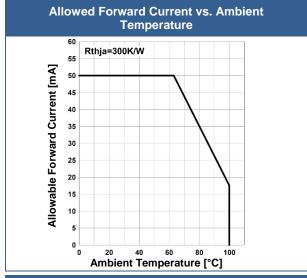
^{*2} measured by CIE127-2007 Condition B

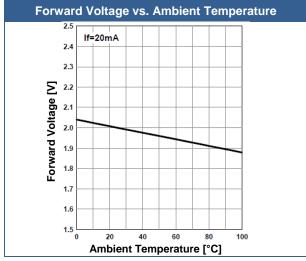
Typical Performance Curves

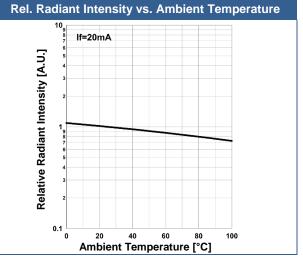










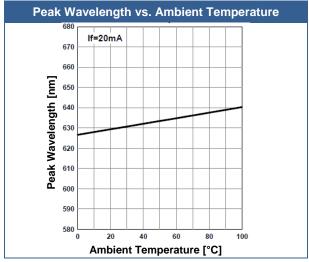


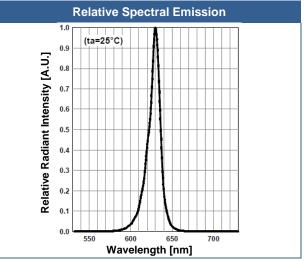


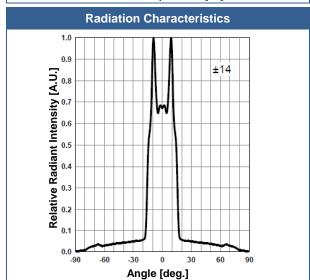
ROITHNER LASERTECHNIK GmbH

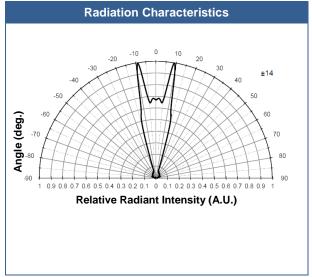
WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM



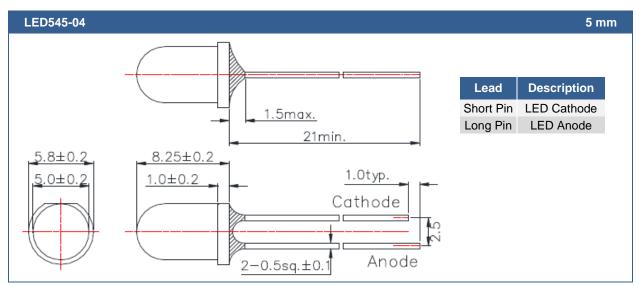








Outline Dimensions



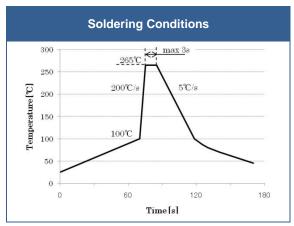
All Dimensions in mm

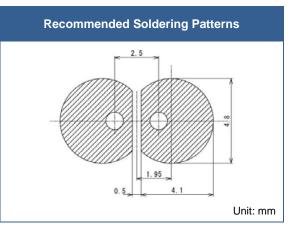
Precautions

Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit light, which could be hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. Protective glasses if needed. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

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